What is claimed is:~~Claims~~

1.~~—~~ (Amended) ~~Components~~A component, comprising: ~~characterized by~~

- a glass substrate~~;—(11)~~
- an organic light-emitting diode~~—(12)~~ arranged on said glass substrate~~—(11),~~; and
- a glass cover~~,—(13) which is~~ arranged over the organic light-emitting diode ~~(12)~~ and ~~is~~ glued at an~~the~~ edge ~~(14)~~ to the glass substrate~~—(11)~~, said cover ~~—~~being produced from a glass plate by three-dimensional removal of material using a ~~sand~~blasting method using commercial crystal corundum having an average particle size of 30 µm and a blasting pressure of 5 bar.

2. (Amended) The ~~C~~component~~s~~ of claim 1, wherein~~characterized in that~~ the edge of the glass cover has been superficially roughened.

3. (Amended) The c~~C~~omponent~~s~~ of claim 1~~—or—2~~, wherein~~characterized in that~~ the glass cover is bonded to the glass substrate using an organic adhesive.

4. (Amended) The c~~C~~omponent~~s~~ of claim 3, wherein~~characterized in that~~ the adhesive is UV-curable.

5. (Amended) The c~~C~~omponent~~s~~ of claim 3~~—or—4~~, wherein~~characterized in that~~ the adhesive is an epoxy resin.

6. ~~6.~~ (Amended) A process for producing a component~~s of one or more of claims 1 to 5~~, comprising:

producing a plurality ~~characterized in that a large number~~ of recesses ~~is produced~~ in a glass plate by three-dimensional removal of material using a ~~sand~~blasting method using commercial crystal corundum having an average particle size of 30 µm and a blasting pressure of

5 bar, said recesses having edges protected by ~~in each case one~~ a resist layer~~,~~;

removing ~~then~~ the protective layer of the edge~~s is removed~~; and

subjecting the edges of the recesses, lying bare, ~~are subjected~~ to a further ~~sand~~blasting method using corundum having an average particle size of 9 µm and a blasting pressure of only 3 bar.

7. (Amended) The process of claim 6, wherein an injector blasting nozzle is used as blasting nozzle in the initial~~first sand~~blasting method.

8. (Amended) The process of ~~one of~~ claim~~s~~ 6 ~~or 7~~, wherein the distance between nozzle and workpiece in the initial ~~first sand~~blasting method is 80 mm.

9. The process of ~~one of~~ claim~~s~~ 6 ~~to 8~~, wherein edges having a roughness of about 30 rms are produced

in the further ~~second sand~~blasting method in a blasting time of 30 seconds.

10. (Amended) The process of ~~one of~~ claim~~s~~ 6~~ to 9~~, wherein after the recesses have been manufactured, the glass plate is used in order to encapsulate a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate, and wherein, following the encapsulation, the resultant components are at least partly individualized.

New Claims

11. ~~,~~The process of claim 6, further comprising:
encapsulating ~~in that using this glass plate~~ a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate using the glass plate, wherein~~is encapsulated, and in~~ tha~~t~~ subse-

——quently ~~the~~ resulting components are at least partly individualized.

12. The component of claim 2, wherein the glass cover is bonded to the glass substrate using an organic adhesive.

13. The component of claim 12, wherein the adhesive is UV-curable.

14. The component of claim 4, wherein the adhesive is an epoxy resin.

15. The component of claim 12, wherein the adhesive is an epoxy resin.

16. The component of claim 13, wherein the adhesive is an epoxy resin.

17. The process of claim 6, wherein the component includes a glass substrate, an organic light-emitting diode arranged on said glass substrate, anda glass cover, arranged over the organic light-emitting diode and glued at an edge to the glass substrate, said cover being produced from a glass plate by the three-dimensional removal of material using the blasting method.

18. The process of claim 6, wherein the glass cover is bonded to the glass substrate using an organic adhesive.

19. The process of claim 18, wherein the adhesive is UV-curable.

20. The process of claim 18, wherein the adhesive is an epoxy resin.

21. The process of claim 19, wherein the adhesive is an epoxy resin.

22. The process of claim 17, wherein the adhesive is an epoxy resin.

99 P 3623
Abstract

~~Components and their production~~

~~The~~A components ~~of the invention comprise the following elements:~~ includes
a glass substrate, ~~(11)~~
an organic light-emitting diode ~~(12)~~ arranged on the~~said~~ glass substrate ~~(11)~~, and
~~a~~ a glass cover ~~(13) which is~~ arranged over the organic light-emitting diode ~~(12)~~. The glass cover ~~and~~ is glued at the edge ~~(14)~~ to the glass substrate. The ~~(11), said~~ cover is one~~being~~ produced from a glass plate by three-dimensional removal of material using a blasting method.

~~FIG 1~~

New claims 1 and 6 to 10

1. Components, characterized by
   - a glass substrate (1)
   - an organic light-emitting diode (12) arranged on said glass substrate (11), and
   - a glass cover (13) which is arranged over the organic light-emitting diode (12) and is glued at the edge (14) to the glass substrate (11), said cover being produced from a glass plate by three-dimensional removal of material using a sandblasting method using commercial crystal corundum having an average particle size of 30 µm and a blasting pressure of 5 bar.

6. A process for producing components of one or more of claims 1 to 5, characterized in that a large number of recesses is produced in a glass plate by three-dimensional removal of material using a sandblasting method using commercial crystal corundum having an average particle size of 30 µm and a blasting pressure of 5 bar, said recesses having edges protected by in each case one resist layer, then the protective layer of the edges is removed and the edges of the recesses, lying bare, are subjected to a further sandblasting method using corundum having an average particle size of 9 µm and a blasting pressure of only 3 bar.

7. The process of claim 6, wherein an injector blasting nozzle is used as blasting nozzle in the first sandblasting method.

8. The process of one of claims 6 or 7, wherein the distance between nozzle and workpiece in the first sandblasting method is 80 mm.

9. The process of one of claims 6 to 8, wherein edges having a roughness of about 30 rms are produced

in the second sandblasting method in a blasting time of 30 seconds.

10. The process of one of claims 6 to 9, wherein after the recesses have been manufactured the glass plate is used in order to encapsulate a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate and where following the encapsulation the resultant components are at least partly individualized.